

## HCMOS 7 x 5mm 3.3V Oscillator

#### Model: FXO-HC73 SERIES

Freq: 0.75 MHz to 250MHz

Rev. 11/28/2007

#### 110V. 11/20/2001



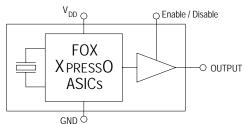


#### **Features**

- XTREMELY Low Jitter
- Low Cost
- XPRESS Delivery
- Frequency Resolution to six decimal places
- Stabilities to ± 20 PPM
- -20 to +70°C or -40 to +85°C operating temperatures
- Tri-State Enable / Disable Feature
- Industry Standard Package, Footprint & Pin-Out
- Fully RoHS compliant

**Description** 

- Gold over Nickel Termination Finish
- Serial ID with Comprehensive Traceability



For more information -- Click on the drawing

# GND O

# The Fox XPRESSO Crystal Oscillator is a breakthrough in configurable Frequency Control Solutions. XPRESSO utilizes a family of proprietary ASICs, designed and developed by Fox, with a key focus on noise reduction technologies.

The 3<sup>rd</sup> order Delta Sigma Modulator reduces noise to the levels that are comparable to traditional Bulk Quartz and SAW oscillators. The ASICs family has ability to select the output type, input voltages, and temperature performance features.

With the XPRESS lead-time, low cost, low noise, wide frequency range, excellent ambient performance, XpressO is an excellent choice over the conventional technologies.

Finished XPRESSO parts are 100% final tested.

# Applications ANY applications

- ANY application requiring an oscillator
- SONET
- Ethernet
- Storage Area Network
- Broadband Access
- Microprocessors / DSP / FPGA
- Industrial Controllers
- Test and Measurement Equipment
- Fiber Channel

#### **Contents**

	page
Model Selection & Part Number Guide	2
Electrical Characteristic	2
Absolute Maximums	3
Output Wave Characteristics	3
Phase Noise	4
Jitter	4
Pin Assignment	5
Recommended Circuit	5
Reflow	5
Mechanical Drawing and Pad Layout	6
Tape and Reel Specification	7
Label	7
Traceability – LOT Number & Serial Identificatior	ո 8
RoHS Material Declaration	9
SGS Report 10	& 11
Mechanical Test	12
Burn-In Test	12
MTTF / FITS calculations	13
Other XPRESSO Links	14
Fox Contact Information	14

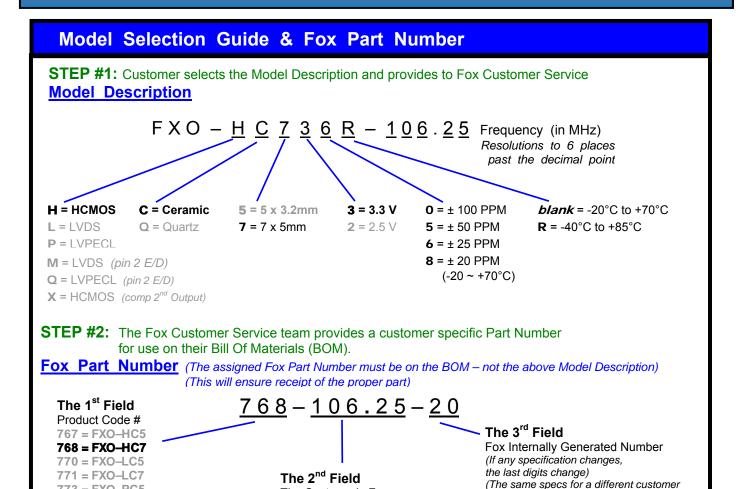


also changes the last digits)



773 = FXO-PC5

774 = FXO-PC7



This example, FXO-HC736R-106.25 = HCMOS Output, Ceramic 7 x 5mm Package, 3.3V, ±25 PPM Stability, -40 to +85°C Temperature Range, at 106.25 MHz

The Customer's Frequency

Electrical Characteristics				
Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)	
Frequency Range	Fo		0.750 to 250.000 MHz	
Frequency Stability <sup>1</sup>			100, 50, 25, & 20 ppm	
Temperature Range	T <sub>O</sub>	Standard operating Optional operating Storage	-20°C to +70°C -40°C to +85°C -55°C to +125°C	
Supply Voltage	$V_{DD}$	Standard	3.3 V ± 5%	
Input Current (@ 15pF LOAD)	I <sub>DD</sub>	0.75 ~ 20 MHz 20+ ~ 50 MHz 50+ ~ 130 MHz 130+ ~ 200 MHz 200+ ~ 250 MHz	32 mA 35 mA 47 mA 55 mA 60 mA	
Output Load	HCMOS	Standard Operational To 125MHz	15 pF 30 pF	
Start-Up Time	Ts		10 mS	
Output Enable / Disable Time			100 nS	
Moisture Sensitivity Level	MSL	JEDEC J-STD-20	1	
Termination Finish			Au	

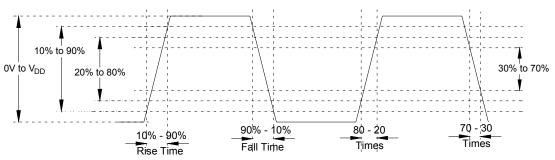


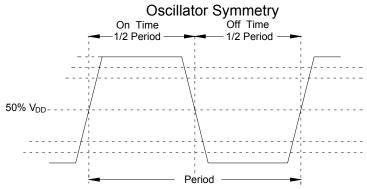
Absolute Maximum Ratings (Useful life may be impaired. For user guidelines only, not tested)				
Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)	
Input Voltage	$V_{DD}$		-0.5V to +5.0V	
Operating Temperature	T <sub>AMAX</sub>		–55°C to +105°C	
Storage Temperature	T <sub>STG</sub>		–55°C to +125°C	
Junction Temperature			150°C	
ESD Sensitivity	HBM	Human Body Model	1 kV	

Output Wave Characteristics					
Parameters	Symbol	Condition	Maximum Value (unless otherwise noted)		
Output LOW Voltage	V <sub>OL</sub>	0.75 to 150 MHz 150+ to 250 MHz	10% V <sub>DD</sub> 20% V <sub>DD</sub>		
Output HIGH Voltage	V <sub>OH</sub>	0.75 to 150 MHz 150+ to 250 MHz	90% V <sub>DD</sub> MIN 80% V <sub>DD</sub> MIN		
Output Symmetry (See Drawing Below)		@ 50% V <sub>DD</sub> Level	45% ~ 55%		
Output Enable (PIN # 1) Voltage	V <sub>IH</sub>		≥70% V <sub>DD</sub>		
Output Disable (PIN # 1) Voltage	V <sub>IL</sub>		≤30% V <sub>DD</sub>		
Cycle Rise Time (See Drawing Below)	T <sub>R</sub>	0.75 to 150 MHz 150+ to 250 MHz	3 nS <sub>(10%~90%)</sub> 3 nS <sub>(20%~80%)</sub>		
Cycle Fall Time (See Drawing Below)	T <sub>F</sub>	0.75 to 150 MHz 150+ to 250 MHz	3 nS <sub>(90%~10%)</sub> 3 nS <sub>(80%~20%)</sub>		

If 30% to 70% times are used, Rise and Fall times change to 1.5 nS from 0.75 to 250MHz If 20% to 80% times are used, Rise and Fall times change to 2 nS from 0.75 to 150MHz

#### Rise Time / Fall Time Measurements

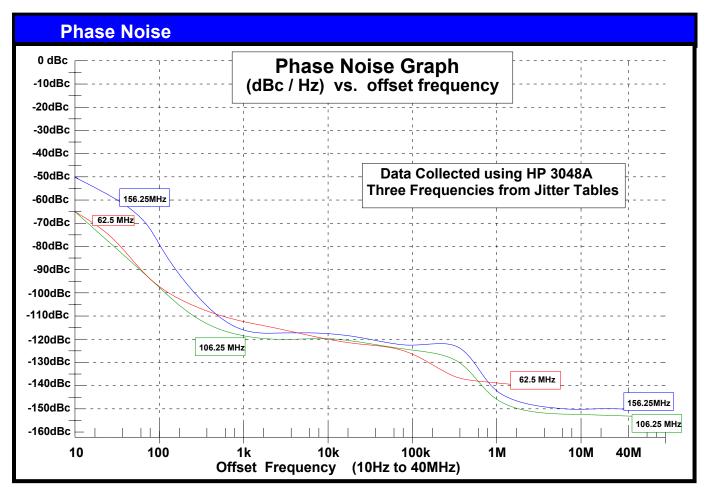




Ideally, Symmetry should be 50/50 -- Other expressions are 45/55 or 55/45







Jitter is frequency dependent. Below are typical values at select frequencies.

Phase Jitter & Time Interval Error (TIE)			
Frequency	Phase Jitter (12kHz to 20MHz)	<b>TIE</b> (Sigma of Jitter Distribution)	Units
62.5 MHz	0.93	2.8	pS RMS
106.25 MHz	0.86	3.2	pS RMS
125 MHz	0.75	2.7	pS RMS
156.25 MHz	0.77	3.3	pS RMS

Phase Jitter is integrated from HP3048 Phase Noise Measurement System; measured directly into 50 ohm input; V<sub>DD</sub> = 3.3V.

TIE was measured on LeCroy LC684 Digital Storage Scope, directly into 50 ohm input, with Amherst M1 software; V<sub>DD</sub> = 3.3V.

Per MJSQ spec (Methodologies for Jitter and Signal Quality specifications)

Random & Deterministic Jitter Composition				
Frequency	Random (Rj)	Deterministic (Dj)	Total Jitter (Tj) (14 x Rj) + Dj	
62.5 MHz	1.28	6.8	25.1 pS	
106.25 MHz	1.28	8.4	26.6 pS	
125 MHz	1.20	8.0	25.2 pS	
156.25 MHz	1.27	8.6	26.6 pS	

Rj and Dj, measured on LeCroy LC684 Digital Storage Scope, directly into 50 ohm input, with Amherst M1 software.

Per MJSQ spec (Methodologies for Jitter and Signal Quality specifications)



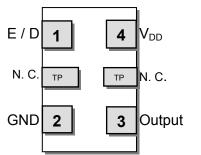


Pin	Pin Description and Recommended Circuit			
Pin#	Name	Type	Function	
1	E/D <sup>1</sup>	Logic	Enable / Disable Control of Output (0 = Disabled)	
2	GND	Ground	Electrical Ground for V <sub>DD</sub>	
3	Output	Output	HCMOS Oscillator Output	
4	V <sub>DD</sub> 2	Power	Power Supply Source Voltage	
Test Points	N. C.	Hi Z	No Connection (Factory Use ONLY)	

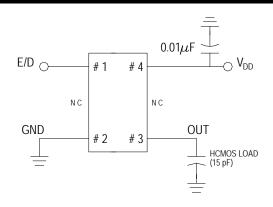
#### **NOTES:**

Includes pull-up resistor to  $V_{DD}$  to provide output when the pin (1) is No Connect.

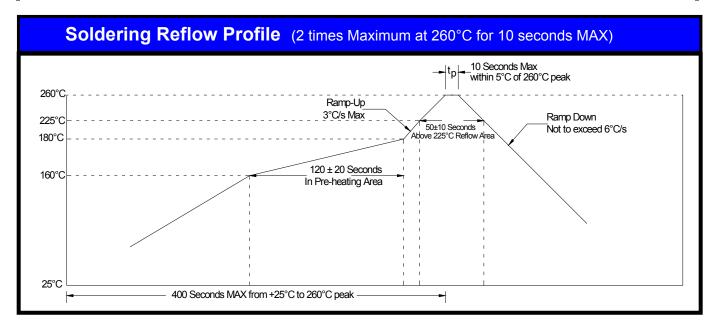
Installation should include a  $0.01\mu F$  bypass capacitor placed between  $V_{DD}$  (Pin 4) and GND (Pin 2) to minimize power supply line noise.



Terminations as viewed from the Top NOTE: XPRESSO HCMOS XOs are designed to fit on Industry Standard, 4 pad layouts



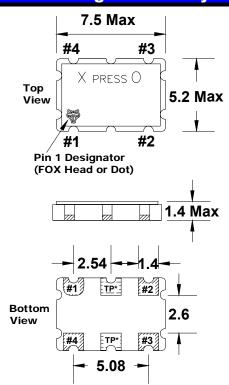
Enable /	Disable Control	
Pir	# 1 (state)	Output (Pin # 3)
0	PEN (No Connection)	ACTIVE Output
"1" L	evel V <sub>IH</sub> > 70% V <sub>DD</sub>	ACTIVE Output
"0" L	evel V <sub>IL</sub> < 30% V <sub>DD</sub>	High Impedance







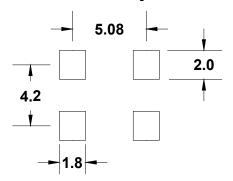
#### Mechanical Dimensional Drawing & Pad Layout



# Actual part marking is depicted.

See **Traceability** (pg. 8) for more information

#### Recommended Solder Pad Layout



Note: XPRESSO HCMOS XOs are designed to fit or industry standard, 4 pad, layouts.

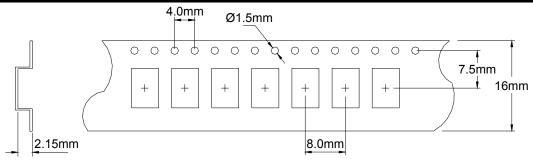
Pin Connections
#1) E/D #3 Output
#2 GND #4 VDD
\*TP are test points and are NC

Drawing is for reference to critical specifications defined by size measurements. Certain non-critical visual attributes, such as side castellations, reference pin shape, etc. may vary

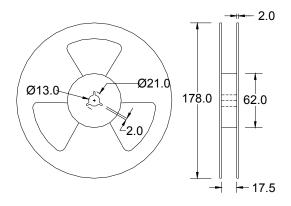




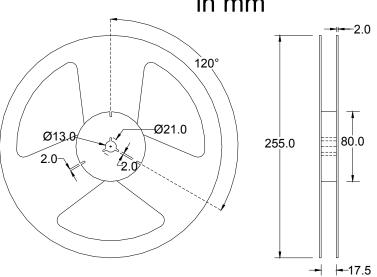
## **Tape and Reel Dimensions**



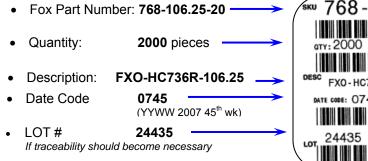
# 1k Reel Dimensions in mm



# 2k Reel Dimensions in mm



#### Labeling (Reels and smaller packaging are labeled with the below)





An additional identification code is contained internally if tracking should ever be necessary





#### Traceability - LOT Number & Serial Identification

#### **LOT Number**

The LOT Number has direct ties to the customer purchase order. The LOT Number is marked on the "Reel" label, and also stored internally on non-volatile memory inside the XPRESSO part. XPRESSO parts that are shipped Tape and Reel, are also placed in an Electro Static Discharge (ESD) bag and will have the LOT Number labeled on the exterior of the ESD bag.

It is recommended that the XPRESSO parts remain in this ESD bag during storage for protection and identification.

If the parts become separated from the label showing the LOT Number, it can be retrieved from inside one of the parts, and the information that can be obtained is listed below:

- Customer Purchase Order Number
- Internal Fox Sales Order Number
- Dates that the XPRESSO part was shipped from the factory
- The assigned customer part number
- The specification that the part was designed for

#### Serial Identification

The Serial ID is the individualized information about the configuration of that particular XPRESSO part. The Serial ID is unique for each and every XPRESSO part, and can be read by special Fox equipment.

With the Serial ID, the below information can be obtained about that individual, XPRESSO part:

- Equipment that the XPRESSO part was configured on
- Raw material used to configure the XPRESSO part
- Traceability of the raw material back to the foundries manufacturing lot
- Date and Time that the part was configured
- Any optimized electrical parameters based on customer specifications
- Electrical testing of the actual completed part
- Human resource that was monitoring the configuration of the part

Fox has equipment placed at key Fox locations World Wide to read the Lot Identification and Serial Number of any XPRESSO part produced and can then obtain the information from above within 24 hours





### **RoHS Material Declaration**

	Material Name	Component	Content	Content	
		·	(mg)	(w t %)	(CAS Number)
Cover	Kovar	Nickel (Ni)	5.09	3.63%	7440-02-0
		Cobalt (Co)	3.15	2.24%	7440-48-4
		Iron (Fe)	9.47	6.75%	7439-89-6
Base	Ceramic	Alumina (Al <sub>2</sub> O <sub>3</sub> )	79.178	56.4%	1344-28-1
		Silicon Oxide (SiO <sub>2</sub> )	3.143	2.24%	14808-60-7
		Chromium Oxide (Cr <sub>2</sub> O <sub>3</sub> )	3.379	2.41%	1308-38-9
		Titanium Oxide (TiO <sub>2</sub> )	0.873	0.622%	13463-67-7
		Magnesium Oxide (MgO)	0.437	0.311%	1309-48-4
		Calcium Oxide (CaO)	0.297	0.212%	1305-78-8
	+ Metallization	Tungsten (W)	12.272	8.74%	7440-33-7
		Molybdenum (Mo)	0.380	0.27%	7439-98-7
	+ Nickel Plating	Nickel (Ni)	4.740	3.38%	7440-02-0
		Cobalt (Co)	0.395	0.28%	7440-48-4
	+ Gold Plating	Gold (Au)	0.624	0.445%	7440-57-5
	+Seal ring	Iron (Fe)	5.809	4.14%	7439-89-6
		Nickel (Ni)	3.119	2.22%	7440-02-0
		Cobalt (Co)	1.829	1.30%	7440-48-4
	+silver solder	Silver (Ag)	2.269	1.62%	7440-22-4
		Copper (Cu)	0.400	0.285%	7440-50-8
I C	I C	Aluminum (Al)	0.0021	0.00150%	7429-90-5
		Silicon (Si)	0.950	0.68%	7440-21-3
	Gold	Gold (Au)	0.480	0.342%	7440-57-5
	Adhesive	Silver (Ag)	0.000210	0.000150%	7440-22-4
		Ероху	0.0000700	0.0000499%	
Crystal	Crystal	Silicon Dioxide (SiO <sub>2</sub> )	2.04	1.45%	14808-60-7
Electrode		Silver (Ag)	0.019	0.0135%	7440-22-4
		Nickel (Ni)	0.000159	0.000113%	7440-02-0
Adhesive		Silver (Ag)	0.00037	0.000264%	7440-22-4
		Silicon (Si)	0.000125	0.000089%	7440-21-3
TOTAL			140.3	100.00%	





#### **Material Report** (SGS)



Test Report No. 2053204/EC Date: Mar 01 2006 Page 1 of 2

FOX ELECTRONICS 5570 ENTERPRISE PARKWAY FT. MYERS, FL 33905

Report on the submitted sample said to be CERAMIC SEAM SEAL OSCILLATOR.

SGS Job No. 1981176

Supplier / Manufacturer FOX ELECTRONICS Sample Receiving Date FEB 17 2006 Testing Period FEB 18 - 24 2006

Test Requested: To determine the Cadmium Content in the submitted sample.

1) 2) 3) To determine the Lead Content in the submitted sample.

To determine the Mercury Content in the submitted sample.

4) 5) To determine the Hexavalent Chromium Content on the submitted sample.

To determine PBBs (polybrominated biphenyls) and PBDEs (Polybrominated diphenylethers) of the submitted sample.

With reference to EPA Method 3051/3052. Test Method 1-3)

Analysis was performed by Inductively Coupled Argon Plasma-Atomic

Emission Spectrometry (ICP-AES).

With reference to EPA Method 3060A & 7196A. 4)

The sample was alkaline digested by using EPA Method 3060A, and then

analyzed by using Colorimetric method 7196A (by UV-Vis

Spectrophotometer).

5) With reference to EPA Method 3540C/ 3550C. Analysis was performed by

GC/MS or LC/ MS.

Test Results 1-5)Please refer to next page.

Signed for and on behalf of SGS Hong Kong Ltd

Ting, Family Laboratory Executive

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SGS Hong Kong Ltd. 5/F - 8/F & 28/F -29/F, Metropole Square, 2 On Ylu Street, Slu Lek Yuen, Shatin, N.T., Hong Kong. t (852) 2334 4481-9 f (852) 2764 3126 www.hk.sgs.com



#### 3rd Party (SGS) Material Report (continued)



Test Report No. 2053204/EC Date: Mar 01 2006 Page 2 of 2

Test Results

 Test Item
 1
 Detection Limit

 1) Cadmium (Cd)
 ND
 2 ppm

 2) Lead (Pb)
 ND
 2 ppm

 3) Mercury (Hg)
 ND
 2 ppm

 4) Hexavalent Chromium (Cr<sup>6+</sup>)
 ND
 2 ppm

(Results shown are of the total weight of samples)

Note: ppm = mg/kg

ND = Not Detected

Not detected is reported when the reading is less than detection limit value

5)

Flame Retardants	1	Detection Limit
Polybrominated Biphenyls (PBBs)		
Monobromobiphenyl	ND	5 ppm
Dibromobiphenyl	ND	5 ppm
Tribromobiphenyl	ND	5 ppm
Tetrabromobiphenyl	ND	5 ppm
Pentabromobiphenyl	ND	5 ppm
Hexabromobiphenyl	ND	5 ppm
Heptabromobiphenyl	ND	5 ppm
Octabromobiphenyl	ND	5 ppm
Nonabromobiphenyl	ND	5 ppm
Decabromobiphenyl	ND	5 ppm
Polybrominated Diphenylethers (PBDEs)		
Monobromodiphenyl ether	ND	5 ppm
Dibromodiphenyl ether	ND	5 ppm
Tribromodiphenyl ether	ND	5 ppm
Tetrabromodiphenyl ether	ND	5 ppm
Pentabromodiphenyl ether	ND	5 ppm
Hexabromodiphenyl ether	ND	5 ppm
Heptabromodiphenyl ether	ND	5 ppm
Octabromodiphenyl ether	ND	5 ppm
Nonabromodiphenyl ether	ND	5 ppm
Decabromodiphenyl ether	ND	5 ppm

Note : ppm = mg/kg

ND = Not Detected

Not detected is reported when the reading is less than detection limit value.

#### Sample Description:

1. Black Ceramic w/ Silvery, Golden Metal w/ Silvery Chips

\*\*\* End of Report \*\*\*

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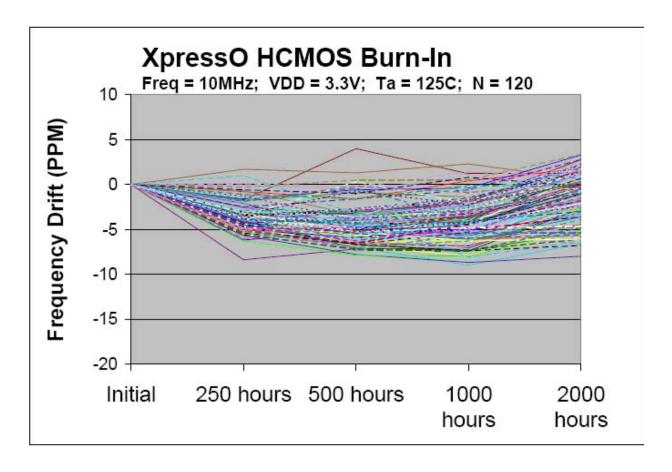


#### **Mechanical Testing**

Parameter Test Method	
Mechanical Shock	Drop from 75cm to hardwood surface – 3 times
Mechanical Vibration	10~55Hz, 1.5mm amplitude, 1 Minute Sweep 2 Hours each in 3 Directions (X, Y, Z)
High Temperature Burn-in	Under Power @ 125°C for 2000 Hours (results below)
Hermetic Seal	He pressure: 4 ±1 kgf / cm <sup>2</sup> 2 Hour soak

#### 2,000 Hour Burn-In

Burn-In Testing – under power 2000 Hours, 125°C







#### MTTF / FITS Calculations

Products are grouped together by process for MTTF calculations. (All XpressO output and package types are manufactured with the same process)

Number of Parts Tested: 360 (120 of each output type: HCMOS, LVDS, LVPECL)

Number of Failures: 0 Test Temperature: 125°C Number of Hours: 2000

MTTF was calculated using the following formulas:

[1.] Device Hours (devhrs) = (number of devices) x (hours at elevated temperature in °K)

[2.] 
$$MTTF = \frac{devhrs \times af \times 2}{\chi^2}$$

[3.] FITS = 
$$\frac{1}{MTTF}$$
 \* 10<sup>9</sup>

Where:

Label	Name	Formula/Value
af	Acceleration Factor	$e^{(rac{eV}{k}) imes(rac{1}{t_1}-rac{1}{t_2})}$
eV	Activation Energy	0.40 V
k	Bolzman's Constant	8.62 X 10 <sup>-5</sup> eV/°K
t <sub>1</sub>		Operating Temperature (°K)
t <sub>2</sub>		Accelerated Temperature (°K)
Θ	Theta	Confidence Level (60% industry standard)
r	Failures	Number of failed devices
χ²	Chi-Square	statistical significance for bivariate tabular analysis [table look-up] based on assumed $\Theta$ (Theta – confidence) and number of failures (r) For zero failures (60% Confidence): $\chi^2 = 1.830$

DEVICE-HOURS = 360 x 2000 HOURS = 720,000

ACCELERATION FACTOR = 
$$e^{(\frac{0.40}{8.625})\times(\frac{1}{298}-\frac{1}{398})}$$
 = 49.91009

MTTF = 
$$\frac{720,000 \times 49.91009 \times 2}{1.833}$$
 = 15,607,065 Hours

Failure Rate = 
$$\frac{1.833}{720,000 \times 49.91009 \times 2}$$
 = 6.41E-8

FITS = Failure Rate \*1E9 = 64





#### Notes

#### Other XPRESSO Links

**XPRESSO Brochure** 

#### **Crystal Oscillators**

HCMOS 5 x 3.2mm 3.3V XO 0.75 to 250MHz

HCMOS 7 x 5mm 3.3V XO 0.75 to 250MHz

LVPECL 5 x 3.2mm 3.3V XO 0.75 to 1.35GHz

LVPECL 7 x 5mm 3.3V XO 0.75 to 1.35GHz

LVDS 5 x 3.2mm 3.3V XO 0.75 to 1.35GHz

LVDS 7 x 5mm 3.3V XO 0.75 to 1.35GHz

#### **Voltage Controlled Crystal Oscillators**

HCMOS 5 x 3.2mm 3.3V VCXO 0.75 to 250MHz
HCMOS 7 x 5mm 3.3V VCXO 0.75 to 250MHz
LVPECL 5 x 3.2mm 3.3V VCXO 0.75 to 1.35GHz
LVPECL 7 x 5mm 3.3V VCXO 0.75 to 1.35GHz
LVDS 5 x 3.2mm 3.3V VCXO 0.75 to 1.35GHz
LVDS 7 x 5mm 3.3V VCXO 0.75 to 1.35GHz

Main Website www.foxonline.com

#### Patent Numbers:

US 6,664,860, US 5,960,403, US 5,952,890; US 5,960,405; US 6,188,290;
Foreign Patents: R.S.A. 98/0866, R.O.C. 120851; Singapore 67081, 67082; EP 0958652
China ZL 98802217.6, Malaysia MY-118540-A, Philippines 1-1998-000245, Hong Kong #HK1026079, Mexico #232179
US and Foreign Patents Pending

XpressO™ Fox Electronics

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The above specifications, having been carefully prepared and checked, is believed to be accurate at the time of publication; however, no responsibility is assumed by Fox Electronics for inaccuracies.